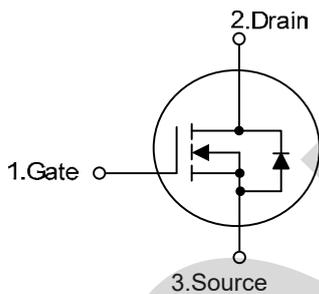
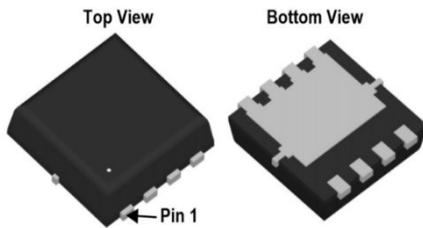


TRENCH N-Channel Enhancement Mode Power MOSFET

MSR4R5N03D33

PDFN3*3-8L



| | | |
|------------------------------|-----|------------|
| V_{DS} | 30 | V |
| $R_{DS(on),TYP@ V_{GS}=10V}$ | 3.6 | m Ω |
| I_D | 90 | A |

Features

- 1、 Low on – resistance
- 2、 Package PDFN3*3-8L
- 3、 TRENCH Power MOSFET

Applications

- 1、 Portable Equipment and Battery Powered systems
- 2、 Power Management in Notebook Computer

Maximum ratings, at TA =25°C, unless otherwise specified

| Symbol | Parameter | Rating | Unit | |
|----------------|---|-------------------|------------|---|
| $V_{(BR)DSS}$ | Drain-Source breakdown voltage | 30 | V | |
| V_{GS} | Gate-Source voltage | ± 20 | V | |
| I_{AS} | Avalanche Current | 42 | A | |
| I_D | Continuous drain current @ $V_{GS}=10V$ | $T_C=25^\circ C$ | 90 | A |
| | | $T_C=100^\circ C$ | 48 | A |
| I_{DM} | Pulse drain current tested | $T_C=25^\circ C$ | 360 | A |
| E_{AS} | Avalanche energy, single pulsed | 39 | mJ | |
| P_D | Maximum power dissipation | $T_C=25^\circ C$ | 81 | W |
| T_{STG}, T_J | Storage and Junction Temperature Range | -55 to 150 | $^\circ C$ | |

Thermal Characteristics

| Symbol | Parameter | Typical | Unit |
|------------------|---|---------|------|
| R _{θJC} | Thermal Resistance, Junction-to-Case | 3.5 | °C/W |
| R _{θJA} | Thermal Resistance, Junction-to-Ambient | 42 | °C/W |

Electrical Characteristics

| Symbol | Parameter | Condition | Min. | Typ. | Max. | Unit |
|--------|-----------|-----------|------|------|------|------|
|--------|-----------|-----------|------|------|------|------|

Static Electrical Characteristics @T_j=25°C (unless otherwise stated)

| | | | | | | |
|---------------------|------------------------------------|--|-----|-----|-----|----|
| V(BR)DSS | Drain-Source Breakdown Voltage | V _{GS} =0V, I _D =250μA | 30 | -- | -- | V |
| I _{DSS} | Zero Gate Voltage Drain Current | V _{DS} =30V, V _{GS} =0V | -- | -- | 1 | μA |
| I _{GSS} | Gate-Body Leakage Current | V _{GS} =±20V, V _{DS} =0V | -- | -- | ±10 | nA |
| V _{GS(th)} | Gate Threshold Voltage | V _{DS} =V _{GS} , I _D =250μA | 1.1 | 1.6 | 2.1 | V |
| R _{DS(on)} | Drain-Source On-State Resistance ④ | V _{GS} =10V, I _D =20A | -- | 3.6 | 4.5 | mΩ |
| | | V _{GS} =4.5V, I _D =18A | -- | 5.3 | 7.2 | mΩ |
| g _{fs} | Forward Transconductance | V _{DS} =5V, I _D =20A | -- | 20 | -- | S |

Dynamic Electrical Characteristics @T_j = 25°C (unless otherwise stated)

| | | | | | | |
|----------------------|------------------------------|---|----|------|----|----|
| C _{iss} | Input Capacitance | V _{DS} =15V, V _{GS} =0V , f=1MHz | -- | 1859 | -- | pF |
| C _{oss} | Output Capacitance | | -- | 260 | -- | pF |
| C _{rss} | Reverse Transfer Capacitance | | -- | 212 | -- | pF |
| R _g | Gate Resistance | V _{DS} =0V, V _{GS} =0V , f=1MHz | -- | 2.2 | -- | Ω |
| Q _g (10V) | Total Gate Charge | V _{DS} =25V, I _D =14A , V _{GS} =10V | -- | 48 | -- | nC |
| Q _{gs} | Gate-Source Charge | | -- | 3.4 | -- | nC |
| Q _{gd} | Gate-Drain Charge | | -- | 14 | -- | nC |

Switching Characteristics

| | | | | | | |
|---------|---------------------|--|----|------|----|----|
| Td(on) | Turn-on Delay Time | V _{DS} =15V, V _{GS} =10V, R _L =1.0Ω, R _G =3.9Ω, | -- | 9.6 | -- | ns |
| Tr | Turn-on Rise Time | | -- | 23.4 | -- | ns |
| Td(off) | Turn-Off Delay Time | | -- | 62.8 | -- | ns |
| Tf | Turn-Off Fall Time | | -- | 23 | -- | ns |

Source -Drain Diode Characteristics @T_j = 25°C (unless otherwise stated)

| | | | | | | |
|-----------------|---------------------------------|---|----|------|-----|----|
| VSD | Forward on voltage | I _S =1A, V _{GS} =0V | -- | 0.7 | 1.1 | V |
| I _S | Diode Forward Current | T _C = 25°C | -- | -- | 90 | A |
| T _{rr} | Reverse Recovery Time (Note1) | I _F =2A , V _{GS} =0V di/dt=100A/μs | -- | 18.2 | -- | ns |
| Q _{rr} | Reverse Recovery Charge (Note1) | | -- | 9.2 | -- | nC |

NOTE:

- ① Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature
- ② Pulse Test: Pulse Width ≤ 300μs, Duty Cycle ≤ 0.5%

■ TYPICAL CHARACTERISTICS

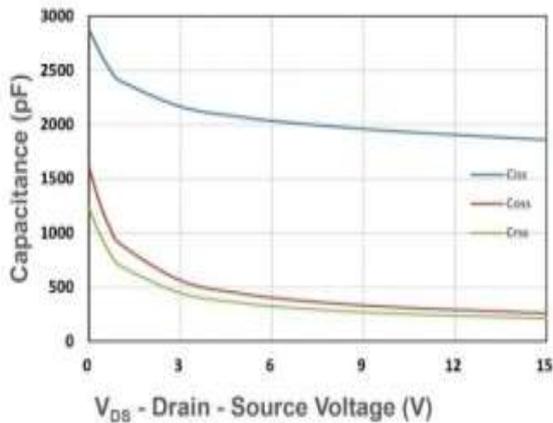


Figure 1. Capacitance

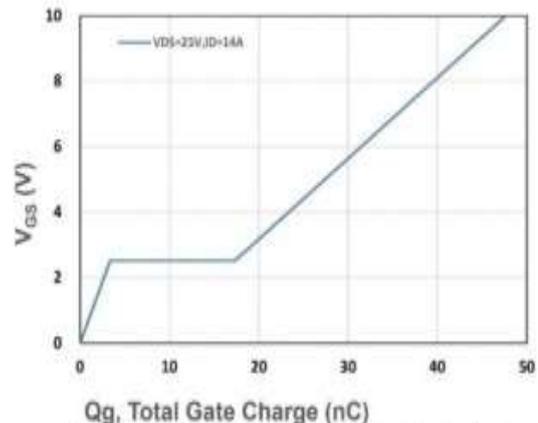


Figure 2. Gate Charge Characteristics

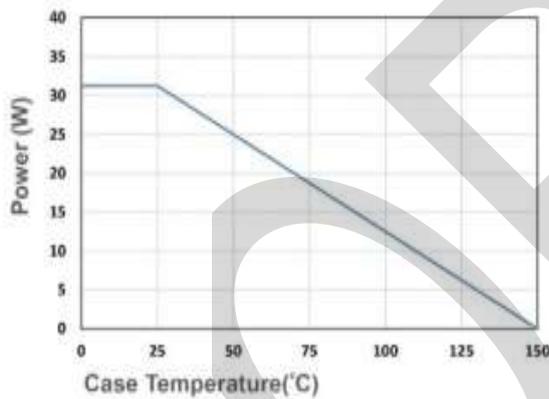


Figure 3. Power Dissipation

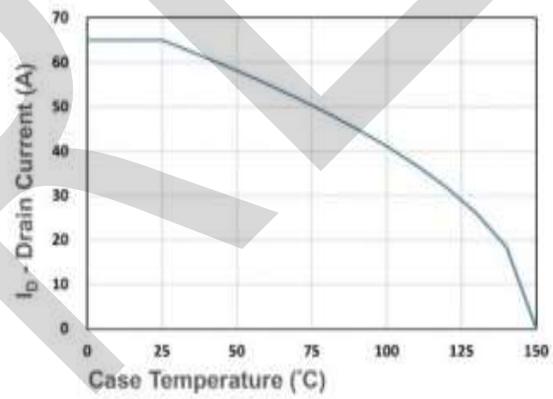


Figure 4. Drain Current

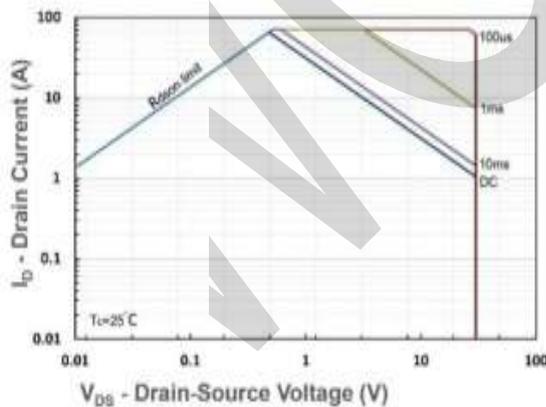


Figure 5. Safe Operating Area

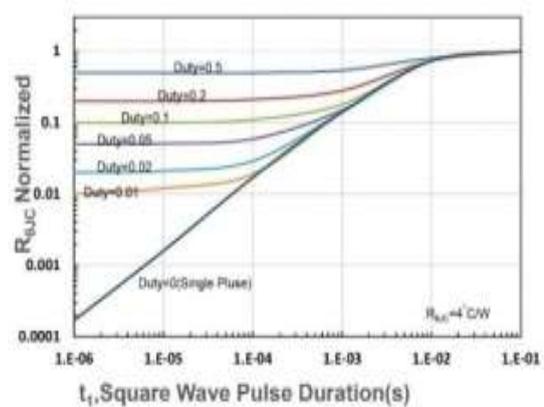
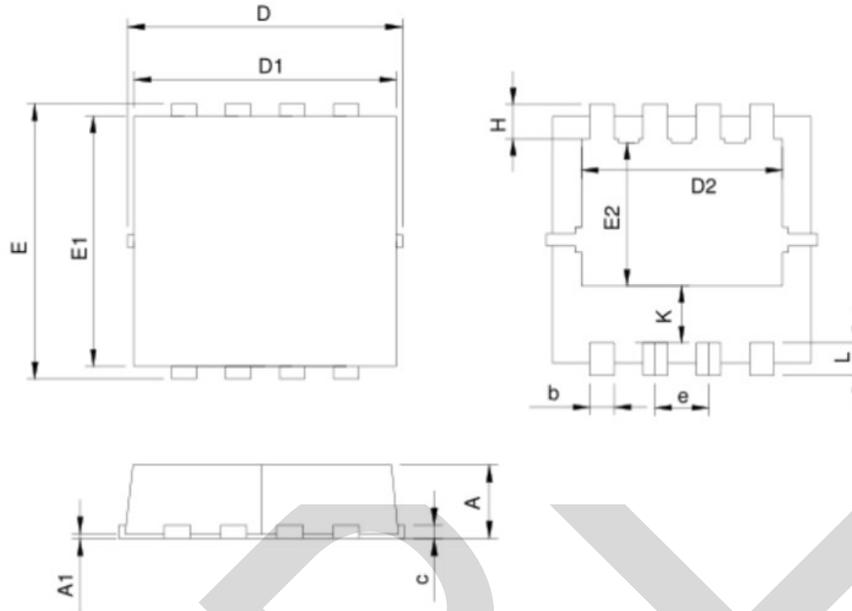


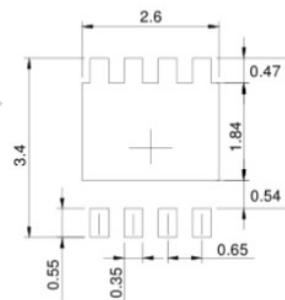
Figure 6. $R_{\theta JC}$ Transient Thermal Impedance

PACKAGE OUTLINE DIMENSIONS



| SYMBOL | DFN3.3x3.3-8 | | | |
|--------|--------------|------|-----------|-------|
| | MILLIMETERS | | INCHES | |
| | MIN. | MAX. | MIN. | MAX. |
| A | 0.70 | 1.00 | 0.028 | 0.039 |
| A1 | 0.00 | 0.05 | 0.000 | 0.002 |
| b | 0.25 | 0.35 | 0.010 | 0.014 |
| c | 0.14 | 0.20 | 0.006 | 0.008 |
| D | 3.10 | 3.50 | 0.122 | 0.138 |
| D1 | 3.05 | 3.25 | 0.120 | 0.128 |
| D2 | 2.35 | 2.55 | 0.093 | 0.100 |
| E | 3.10 | 3.50 | 0.122 | 0.138 |
| E1 | 2.90 | 3.10 | 0.114 | 0.122 |
| E2 | 1.64 | 1.84 | 0.065 | 0.072 |
| e | 0.65 BSC | | 0.026 BSC | |
| H | 0.32 | 0.52 | 0.013 | 0.020 |
| K | 0.59 | 0.79 | 0.023 | 0.031 |
| L | 0.25 | 0.55 | 0.010 | 0.022 |

RECOMMENDED LAND PATTERN



UNIT: mm